

Singapore Asahi Chemical & Solder Industries Pte Ltd Asahi Products-Core Wire

	Formula Type	CLF5013	CLF5023	CLF5033	HCLF490	HCLF491	CLF5160	CLF92	CLF4128	CF60	CF10/ CF10A	C6
	Alloy Compatibility	V347, V349, SAC305, SAC0307, SCS7, SnAg3.5, SnAg3.0, SnCu3.0, SnCu0.7								SnPb		
Product Features		CLF5013 is a halide free no-clean core flux designed for superior solderability on difficult to solder metals.	CLF5023 provides instant wetting action and excellent solderability on variety of surface finishes.	CLF5033 is designed for improved wettability, minimal smoke and odor. The flux splattering is low and the flux residue does not charr at the solder iron tip.	HCLF490 is designed for normal and high temperature soldering. Under high soldering temperature, the flux residue does not charr easily yet offers superior wetting characteristic.	HCLF491 is designed for normal and high temperature application in manual or auto soldering. The flux residue is light yellowish even at high temperature yet provides excellent wetting characteristic.	CLF5160 is formulated using purest chemical which guarantees absolute flux core continuity and consistency in solder properties.	CLF92 is formulated using purest chemical together with halogen free materials, which guarantees absolute flux core continuity and consistency in solder properties.	CLF4128 is a highly activated water soluble core flux for soldering on difficult to solder surface finishes. It is easily cleaned along with minimal odor and smoke.	CF60 gives a non-corrosive, minimal, clear yellow tinted residue which exhibits excellent electrical and thermal insulation properties.	CF10/CF10A are an activated rosin formula for use in flux-core solder wire. This cored flux exhibits the so-called "instant action" wetting behaviour. The high mobility and fast spreading action of this flux result in fast production line soldering.	C6 is a highly activated water soluble core flux for soldering on difficult to solder surface finishes. It is easily cleaned along with minimal odor and smoke.
Properties	Flux Content (wt%)	2.0, 2.5, 3.0	2.0, 2.5, 3.0	2.0, 2.5, 3.0	2.0, 2.5, 3.0, 3.5, 4.0	2.0, 2.5, 3.0	2.0, 2.5, 3.0, 3.5, 4.0	2.5, 3.0	3.0	2.0	2.0	2.3
	Halide Content (wt%) JIS Z 3197 8.1.4.2.1	Not Added	Not Added	Not Added	Not Added	Not Added	Not Added	Not Added	0.4 ± 0.1	Not Added	0.7/0.45	1
	Copper Corrosion Test JIS Z 3197 8.4.1	Passed	Passed	Passed	Passed	Passed	Passed	Passed	Passed	Passed	Passed	Passed
	SIR (85°C, 85%RH,168hrs) IPC-TM-650 2.6.3.3	>1 x 10 ⁸ Ω	>1 x 10 ⁸ Ω	>1 x 10 ⁸ Ω	>1 x 10 ⁸ Ω	>1 x 10 ⁸ Ω	>1 x 10 ⁸ Ω	>1 x 10 ⁸ Ω	>1 x 10 ⁸ Ω	>1 x 10 ⁸ Ω	>1 x 10 ⁸ Ω	>1 x 10 ⁸ Ω
	ECM (85°C, 88.5%RH, 596hrs) IPC-TM-650 2.6.14.1	>1 x 10 ⁸ Ω No Dentrite Growth	>1 x 10 ⁸ Ω No Dentrite Growth	>1 x 10 ⁸ Ω No Dentrite Growth	>1 x 10 ⁸ Ω No Dentrite Growth	>1 x 10 ⁸ Ω No Dentrite Growth	>1 x 10 ⁸ Ω No Dentrite Growth	>1 x 10 ⁸ Ω No Dentrite Growth	>1 x 10 ⁸ Ω No Dentrite Growth	>1 x 10 ⁸ Ω No Dentrite Growth	>1 x 10 ⁸ Ω No Dentrite Growth	>1 x 10 ⁸ Ω No Dentrite Growth
	Flux Activity Classification IPC J-STD-004	ROMO	ROLO	ROMO	ROMO	ROLO	ROLO	ROMO	ROH1	ROLO	ROH1	ROH1
	Spread Factor JIS Z 3197 8.3.1.1	>80%	>80%	>80%	>75%	>75%	>75%	>70%	>75%	>80% (SnPb)	>80% (SnPb)	>80% (SnPb)
	Residue Appearance	Yellowish	Light Yellowish	Light Yellowish	Light Yellowish	Light Yellowish	Light Yellowish	Light Yellowish	Light Yellowish	Light Yellowish	Light Yellowish	Light Yellowish
	Residue Removal	Not Required	Not Required	Not Required	Not Required	Not Required	Not Required	Not Required	Rinse with DI water at 40°C-60°C	Not Required	Not Required	Rinse with DI water at 40°C-60°C
Applications	Manual Soldering	•	•	•	•	•	•	•	•	•	•	•
	Auto Soldering	•	•	•	•	•	•	•	•	•	•	•